

## 800V N-Channel MOSFET

### Description

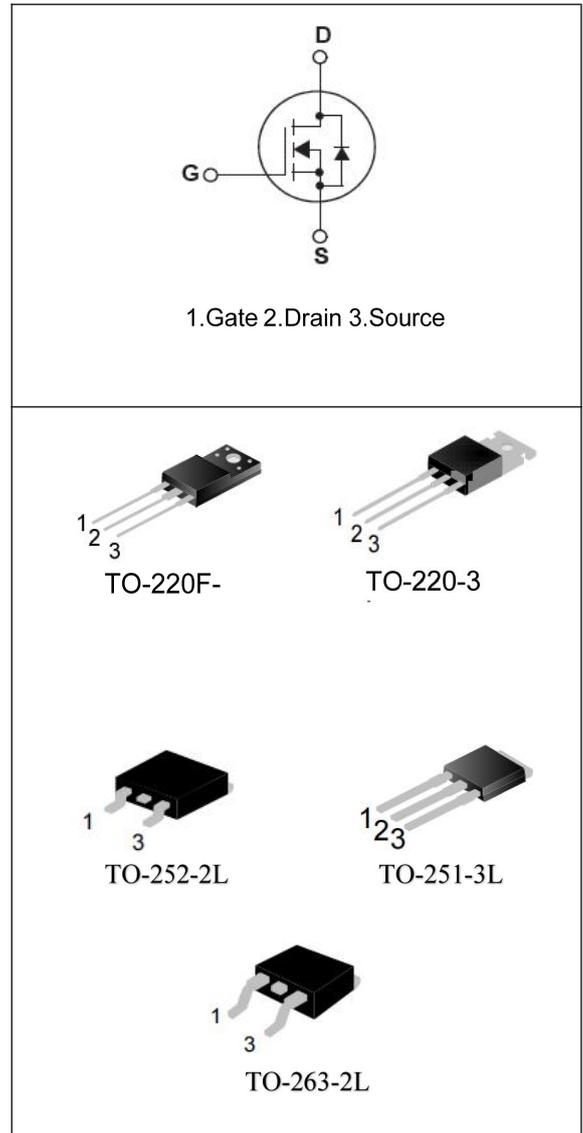
SSMOS-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy.

SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

### Features

- Multi-Epi process SJ-FET
- 850V@T<sub>J</sub>=150°C
- Typ. R<sub>DS(on)</sub>=0.8Ω(TO-220F)
- Ultra Low Gate Charge (typ. Q<sub>g</sub>=9.5nC)
- 100% avalanche tested



### Package Marking and Ordering Information:

Marking	Package	Part #	Hazardous Substance Control	Packing
SR80R850F	T0-220F-3L	SR80R850F	Pb free	Tube
SR80R850T	T0-220-3L	SR80R850T	Pb free	Tube
SR80R850D	TO-252-2L	SR80R850D	Halogen free	Reel
SR80R850M	TO-251-3L	SR80R850M	Halogen free	Tube
SR80R850S	TO-263-2L	SR80R850S	Halogen free	Reel

**Absolute Maximum Ratings**

Symbol	Parameter	SR80R850T/D/M/S	SR80R850F	Unit
VDSS	Drain-Source Voltage	800		V
ID	Drain Current-Continuous(TC=25℃)	6.6*		A
	-Continuous(TC=100℃)	4.2*		
IDM	Drain Current-Pulsed(Note1)	20*		A
VGSS	Gate-Source Voltage	±30		V
EAS	Single Pulsed Avalanche Energy(Note2)	86		mJ
IAR	Avalanche Current(Note1)	1.7		A
EAR	Repetitive Avalanche Energy(Note1)	0.2		mJ
DV/DT	Peak Diode Recovery DV/DT(Note3)	15		V/ns
DV/DS/DT	Drain Source Voltage Slope(Vds=640V)	50		V/ns
PD	Power Dissipation(TC=25℃)	63	28	W
TJ,TSTG	Operating and Storage Temperature Range	-55to+150		℃
TL	Maximum Lead Temperature for Soldering Purpose,1/8"from Case for 5 Seconds	300		℃

\* Drain current limited by maximum junction temperature . Maximum duty cycle D=0.75.

**Thermal Characteristics**

Symbol	Parameter	SR80R850T/D/M/S	SR80R850F	Unit
RθJC	Thermal Resistance, Junction-to-Case	2.0	4.5	℃/W
RθCS	Thermal Resistance, Case-to-Sink Typ	0.5	-	℃/W
RθJA	Thermal Resistance, Junction-to-Ambient	62	80	℃/W

**Electrical Characteristics TC = 25°C** unless otherwise noted

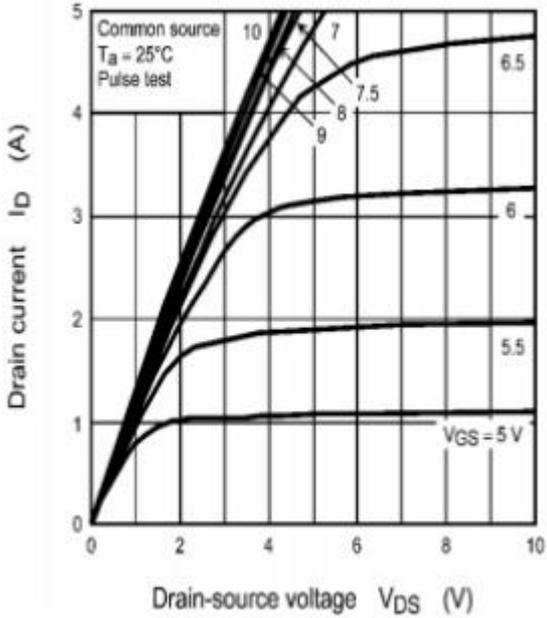
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250uA Tj=25°C	800	-	-	V
		VGS=0V, ID=250uA Tj=150°C	-	850	-	V
BVDSS/TJ	Breakdown Voltage Temperature Coefficient	ID=250uA, Referenced to 25°C	-	0.6	-	V/°C
IDSS	Zero Gate Voltage Drain Current	VDS=800V, VGS=0V TJ=150°C	-	- 10	1 -	uA uA
IGSSF	Gate-Body Leakage Current, Forward	VGS=30V, VDS=0V	-	-	100	nA
IGSSR	Gate-Body Leakage Current, Reverse	VGS=-30V, VDS=0V	-	-	-10 0	nA
<b>On Characteristics</b>						
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250uA	2.5	3.5	4.5	V
RDS(on)	Static Drain-Source On-Resistance	VGS=10V, ID=3.5A (TO-220F/TO-220/TO-263)	-	0.8	0.9	Ω
		VGS=10V, ID=5.5A (TO-251/TO-252)	-	0.85	0.93	Ω
gFS	Forward Transconductance	VDS=40V, ID=7A	-	6	-	S
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS=25V, VGS=0V, f=1.0MHz	-	380	-	pF
Coss	Output Capacitance		-	115	-	pF
Crss	Reverse Transfer Capacitance		-	9	-	pF
<b>Switching Characteristics</b>						
td(on)	Turn-On Delay Time	VDS=400V, ID=3.5A RG=25Q, (Note4)	-	23	-	ns
tr	Turn-On Rise Time		-	19	-	ns
td(off)	Turn-Off Delay Time		-	44	-	ns
tf	Turn-Off Fall Time		-	18	-	ns
Qg	Total Gate Charge	VDS=450V, ID=3.5A VGS=10V, (Note4)	-	9.5	-	nc
Qgs	Gate-Source Charge		-	1.9	-	nc
Qgd	Gate-Drain Charge		-	4.5	-	nc
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
IS	Maximum Continuous Drain-Source Diode Forward Current		-	-	7	A
ISM	Maximum Pulsed Drain-Source Diode Forward Current		-	-	20	A
VSD	Drain-Source Diode Forward voltage	VGS=0V, IS=7A	-	0.9	1.5	V
Trr	Reverse Recovery Time	VR=400V, VGS=0V IF=7A, dIF/dt=100A/us	-	550	-	ns
Qrr	Reverse Recovery Charge		-	4.8	-	uC
Irrm	Peak Reverse Recovery Current		-	15.5	-	A

**NOTES:**

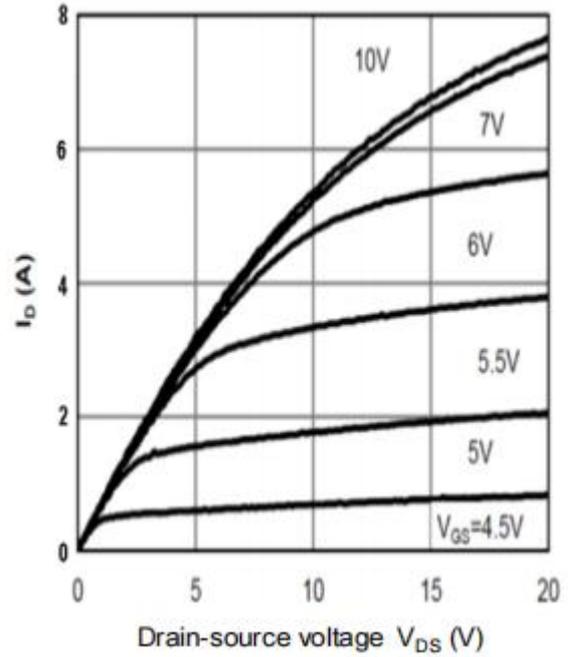
- 1.Repetitive Rating:Pulse width limited by maximum junction temperature;
- 2.IAS=1.7A,VDD=50V,Starting TJ=25°C ;
- 3.ISD $\leq$ ID,di/dt $\leq$ us,VDD $\leq$ BVDSS,Starting TJ=25°C ;
- 4.Essentially Independent of Operating Temperature Typical Characteristics.

**Typical Performance Characteristics**

Figuer1:On-Region Characteristics@25°C

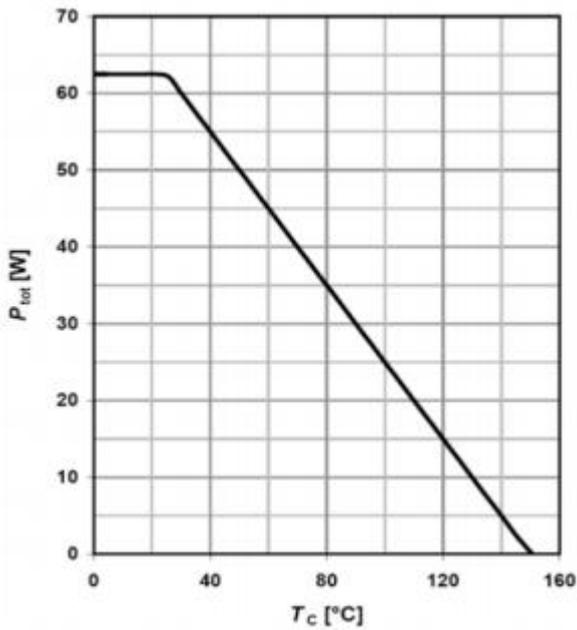


Figuer2:On-Region Characteristics@125°C



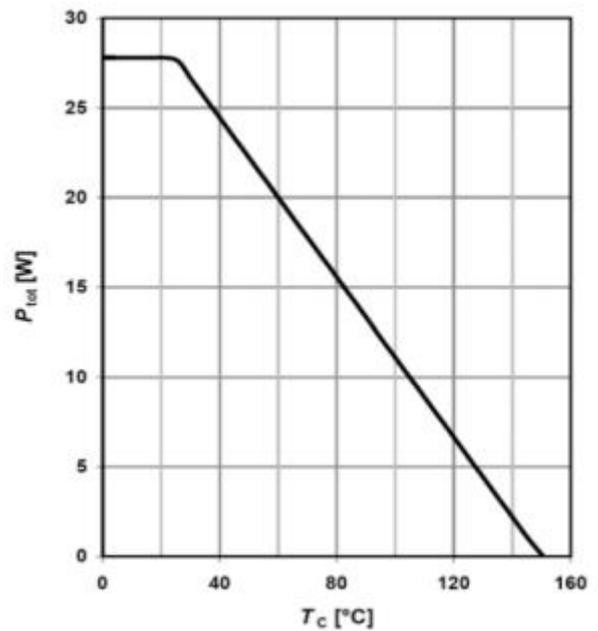
Figuer3:Power Dissipation

TO-220,TO-252,TO-251,TO-263



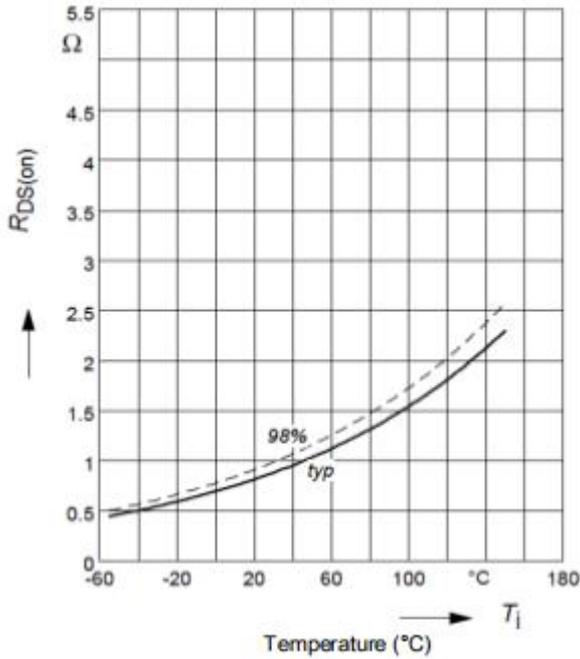
Figuer4:Power Dissipation

TO-220FullPAK

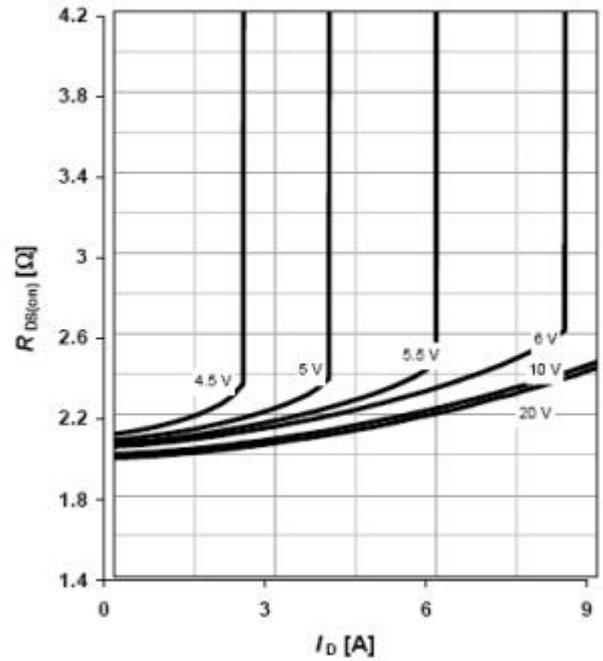


**Typical Performance Characteristics**

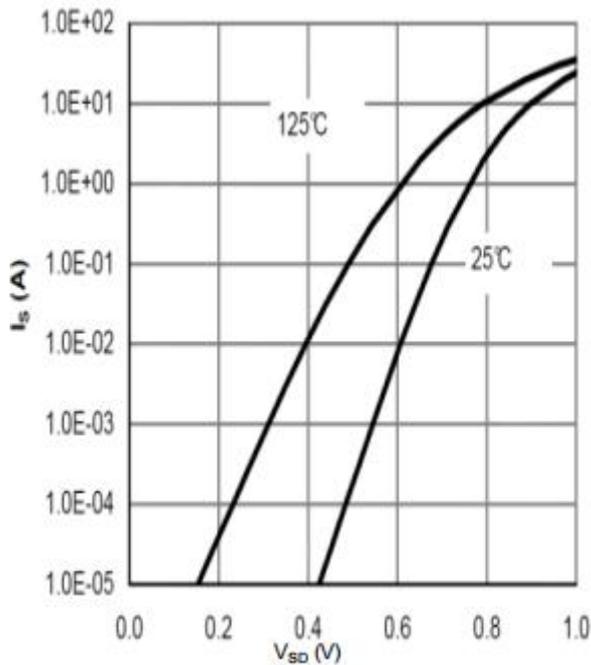
Figuer5:On-Resistance vs.  
 Junction Temperature  
 TO-220FullPAK



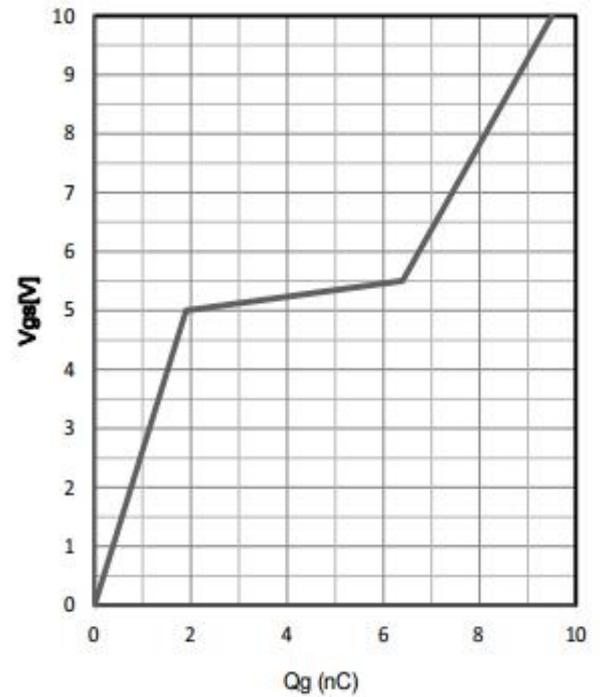
Figuer6:On-Resistance vs.  
 Drain Current,  $T_j=150^{\circ}C$



Figuer7:Body-Diode Characteristics

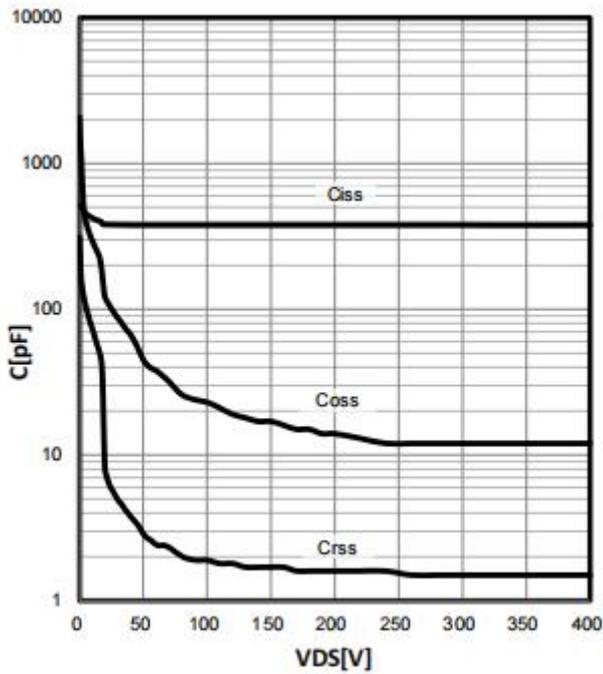


Figuer8:Gate-Charge Characteristics

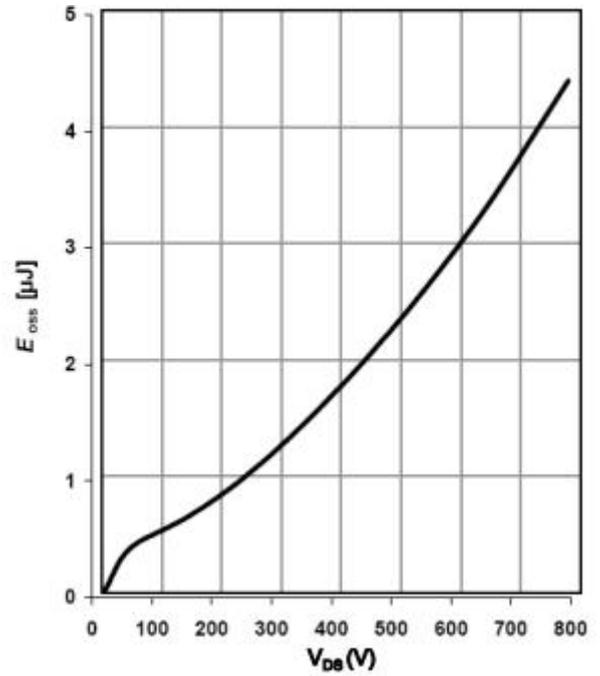


Typical Performance Characteristics

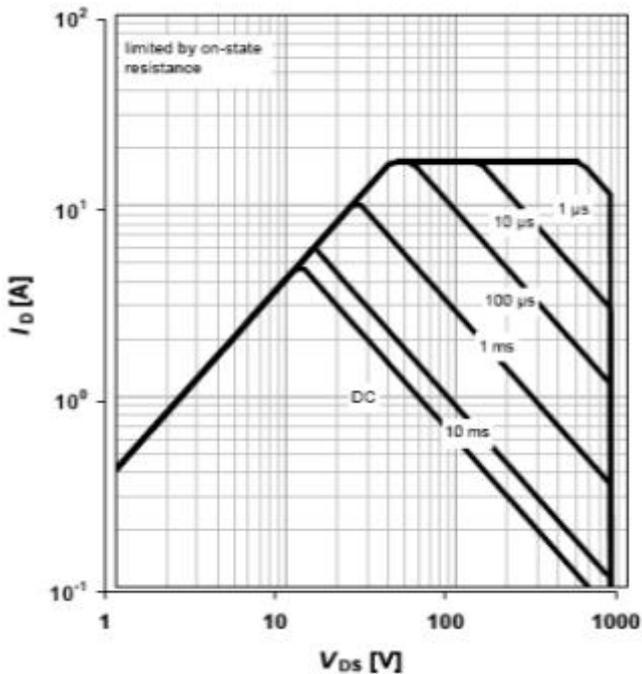
Figuer9:Capacitance Characteristics



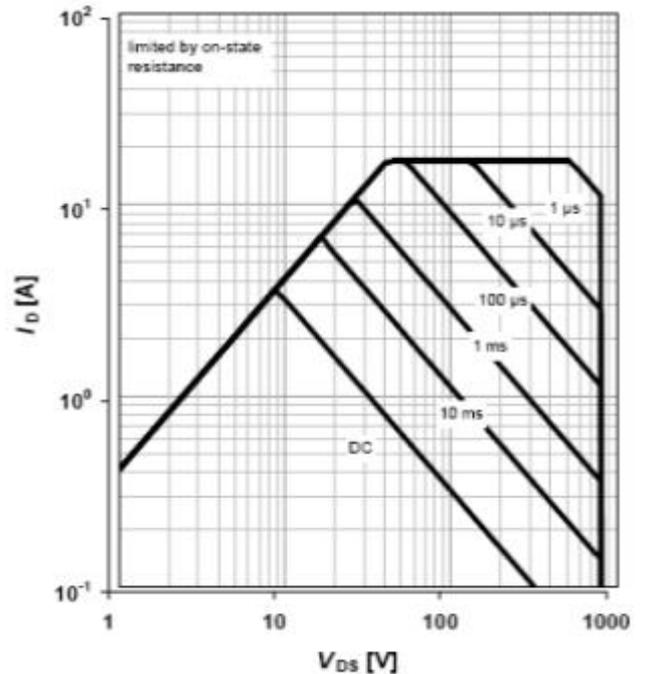
Figuer10:Coss stored Energy



Figuer11:Maximum Forward Biased Safe Operating Area Tc=25°C, TO-220,TO-2252,TO251,TO-263

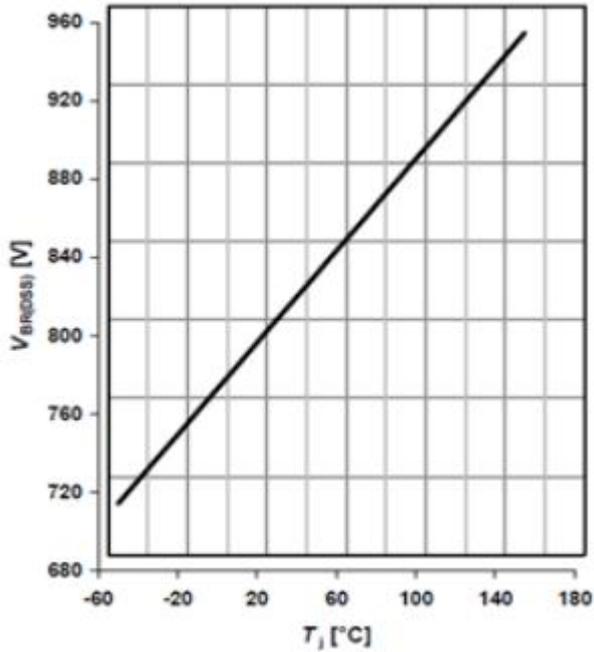


Figuer12:Maximum Forward Biased Safe Operating Area Tc=25°C, TO-220 FullPAK

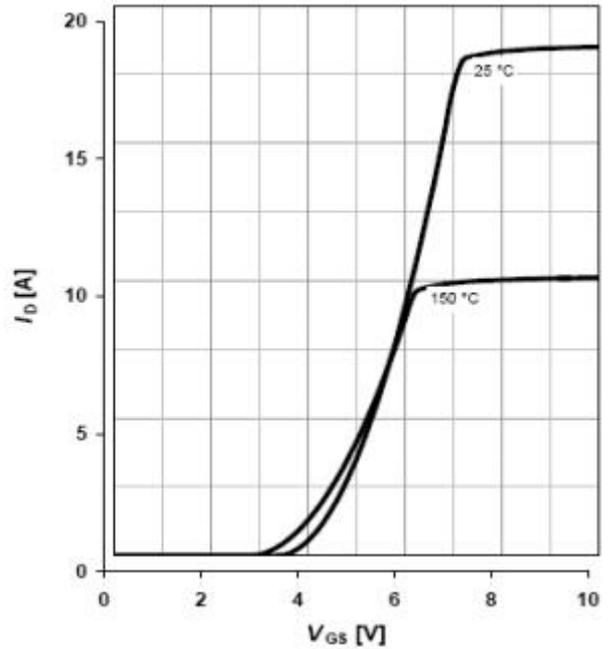


**Typical Performance Characteristics**

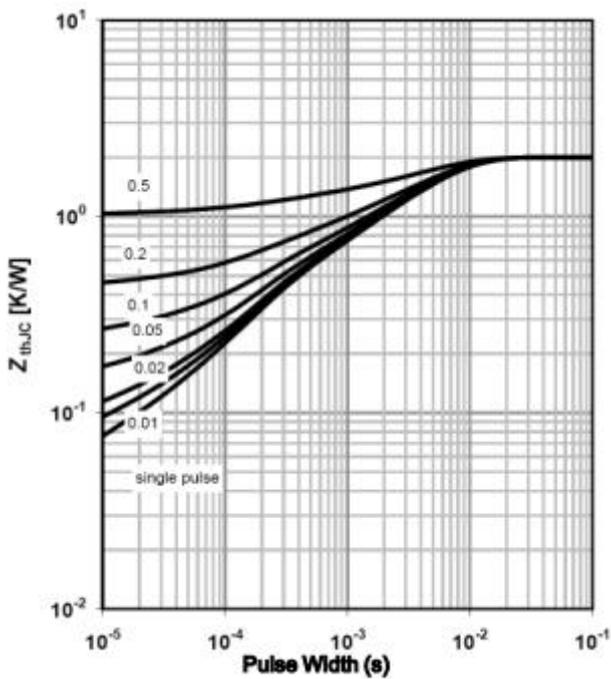
Figuer13:Break Down vs. Junction Temperature



Figuer14:Typical transfer characteristics



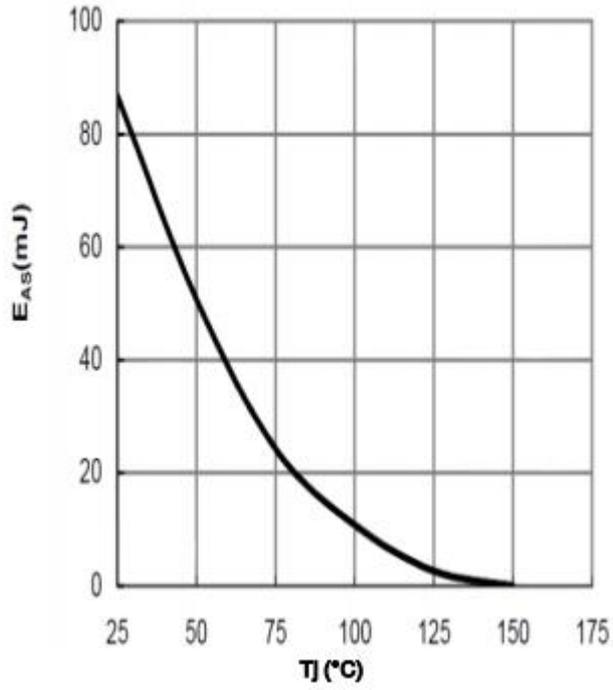
Figuer15:Maximum Transient Thermal Impedance TO-220,TO-252,TO-251, TO-263



Figuer16:Maximum Transient Thermal Impedance TO-220 FullPAK

## Typical Performance Characteristics

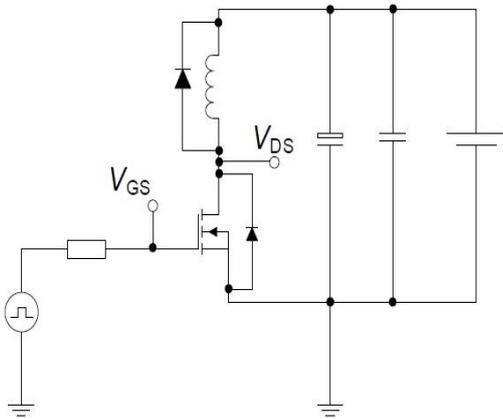
Figuer17:Avalanche energy



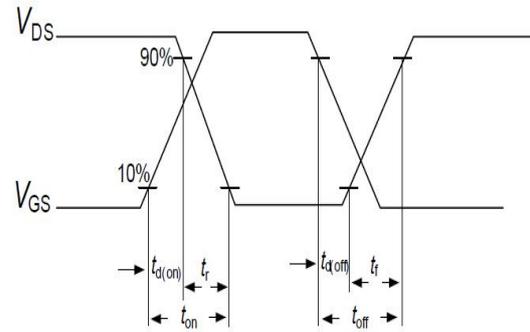
### Test circuits

#### Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

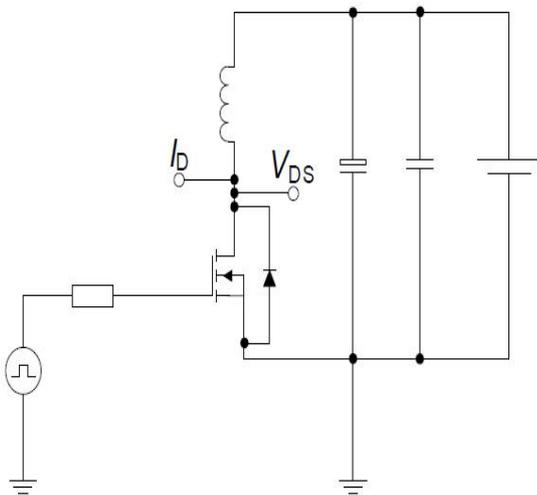


Switching time waveform

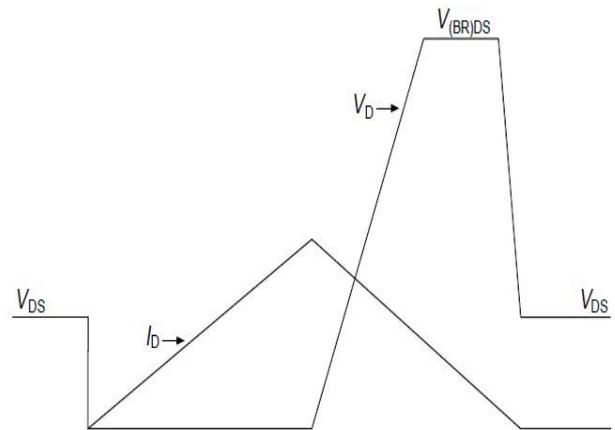


#### Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit



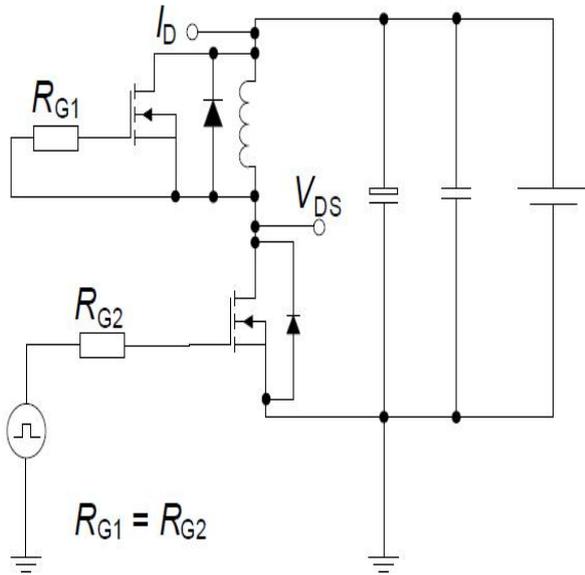
Unclamped inductive waveform



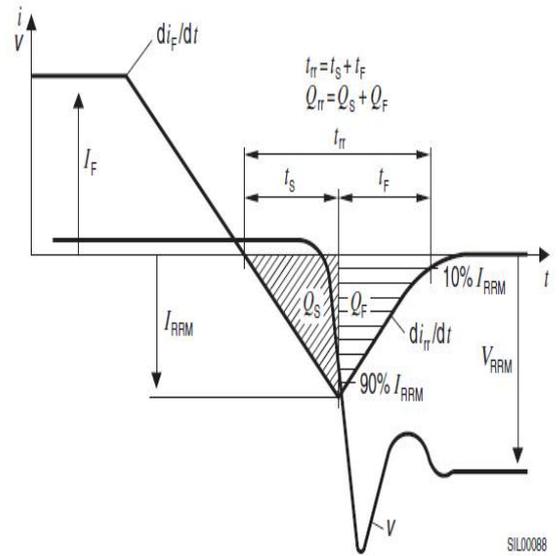
**Test circuits**

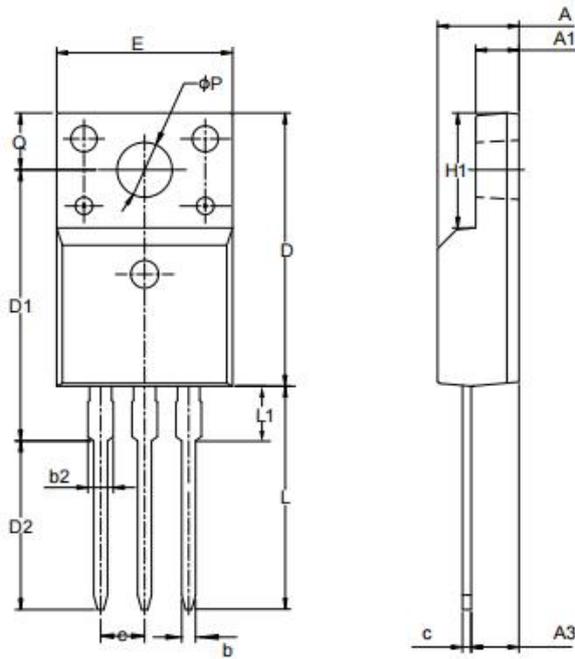
Test circuit and waveform for diode characteristics

Test circuit for diode characteristics

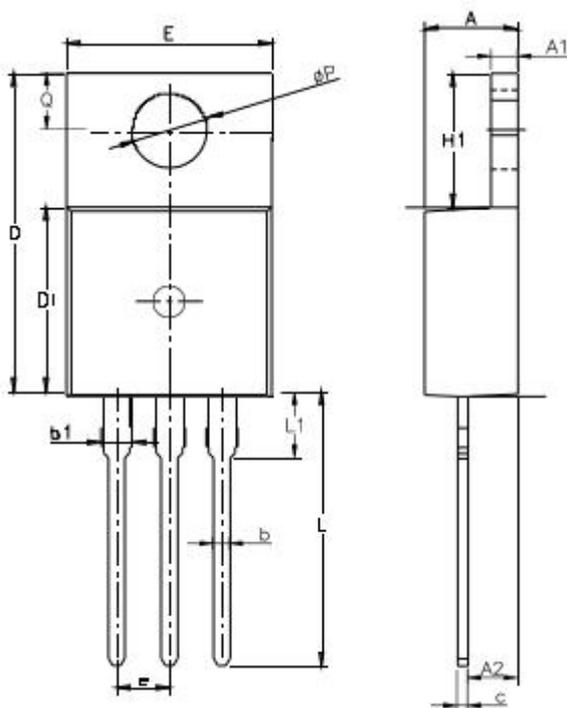


Diode recovery waveform

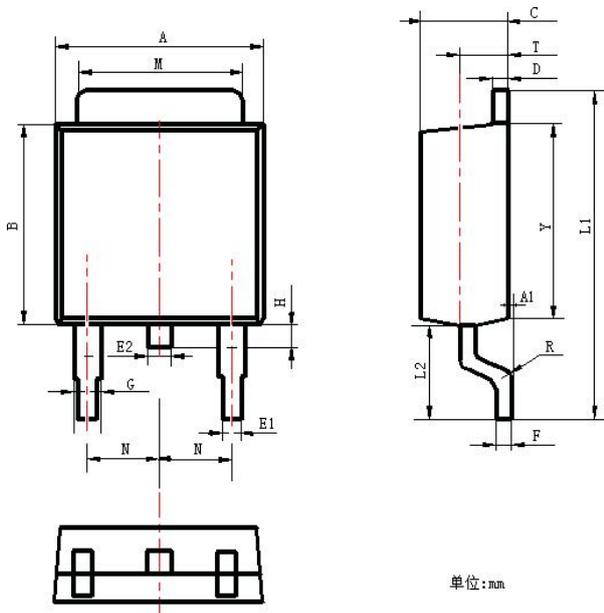


**Package Outline**
**TO-220 Full PAK**


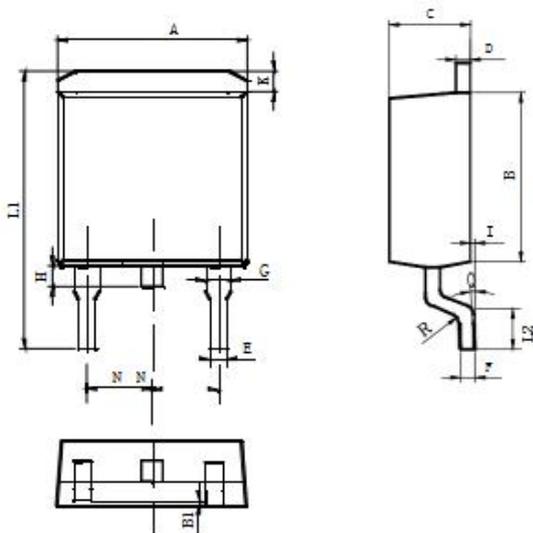
COMMON DIMENSIONS			
Items	Values(mm)		
	MIN	NOM	MAX
A	4.42	4.7	5.02
A1	2.3	2.54	2.8
A3	2.5	2.76	3.1
b	0.7	0.8	0.9
b2	--	--	1.47
c	0.35	0.5	0.65
D	15.25	15.87	16.25
D1	15.3	15.75	16.3
D2	9.3	9.8	10.3
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.4	6.68	7
L	12.48	12.98	13.48
L1	--	--	3.5
$\phi P$	3	3.18	3.4
Q	3.05	3.3	3.55

**TO-220-3L**


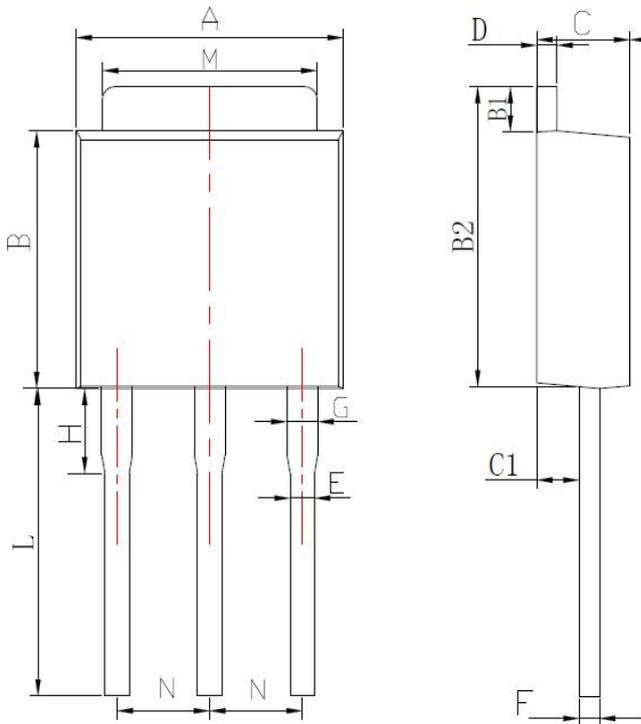
COMMON DIMENSIONS			
Items	Values(mm)		
	MIN	NOM	MAX
A	4.3	4.5	4.7
A1	1	1.3	1.5
A2	1.8	2.4	2.8
b	0.6	0.8	1
b1	1	-	1.6
c	0.3	-	0.7
D	15.1	15.7	16.1
D1	8.1	9.2	10
F	9.6	9.9	10.4
e	2.54BSC		
H1	6.1	6.5	7
L	12.6	13.08	13.6
L1			3.95
$\phi P$	3.4	3.7	3.9
Q	2.6		3.2

**Package Outline**
**TO-252-2L**


COMMON DIMENSIONS			
Items	Values(mm)		
	MIN	NOW	MAX
A	6.3	6.5	6.9
A1	0	-	0.16
B	5.7	-	6.3
C	2.1	2.3	2.5
D	0.3	0.5	0.7
E1	0.6	0.65	0.9
E2	0.7	0.65	1
F	0.3	0.5	0.6
G	0.7	0.9	1.2
L1	9.6	10	10.5
L2	2.7	-	3.1
H	0.4	-	1
M	5.1	5.2	5.5
N	2.09	2.2	2.49
R	0.3		
T	1.4	-	1.6
Y	5.1	5.9	6.3

**TO-263-2L**


COMMON DIMENSIONS			
Items	Values(mm)		
	MIN	NOW	MAX
A	9.8	10	10.4
B	8.9	9.6	9.5
B1	0	-	0.1
C	4.4	4.5	4.8
D	1.16	1.4	1.5
E	0.7	0.75	0.95
F	0.3	0.45	0.6
G	1.07	1.38	1.47
H	1.3	-	1.8
K	0.95	1	1.37
L1	14.5	15.2	16.5
L2	1.6	2	2.3
I	0	-	0.2
Q	0°	3°	8°
R	0.4		
N	2.35	2.4	2.7

**Package Outline**
**TO-251-3L**


COMMON DIMENSIONS			
Items	Values(mm)		
	MIN	NOW	MAX
A	6.3	6.5	6.9
B	5	5.2	6.3
B1	0.7	1.1	1.3
B2	6.8	7.2	7.4
C	2.1	2.3	2.5
C1	0.9	-	1.2
D	0.3	0.5	0.6
E	0.5	0.65	0.86
F	0.3	0.5	0.6
G	0.7	-	1
H	1.4	2	2.4
L	9	9.4	9.8
M	5.1	5.2	5.5
N	2.09	2.2	2.49